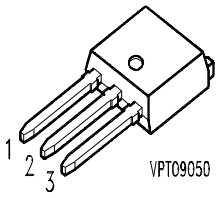
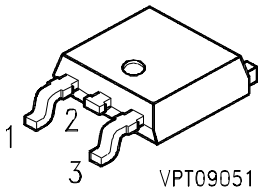
SIPMOS ® Power Transistor

- N channel
- Enhancement mode
- Avalanche-rated





Pin 1	Pin 2	Pin 3
G	D	S

Type	V_{DS}	I_D	$R_{DS(on)}$	Package	Ordering Code
SPD08N10	100 V	8.4 A	0.3 Ω	P-TO252	Q67000-. . . - . .
SPU08N10	100 V	8.4 A	0.3 Ω	P-TO251	Q67000-. . . - . .

Maximum Ratings

Parameter	Symbol	Values	Unit
Continuous drain current T_C = 25 °C	I_D	8.4	A
Pulsed drain current T_C = 25 °C	I_{Dpuls}	33.6	
Avalanche energy, single pulse I_D = 8.4 A, V_{DD} = 25 V, R_{GS} = 25 Ω L = 850 µH, T_j = 25 °C	E_{AS}	30	mJ
Gate source voltage	V_{GS}	± 20	V
Power dissipation T_C = 25 °C	P_{tot}	40	W
Operating temperature	T_j	-55 ... + 150	°C
Storage temperature	T_{stg}	-55 ... + 150	
Thermal resistance, junction - case	R_{thJC}	≤ 3.1	K/W
Thermal resistance, junction - ambient (PCB mount)**	R_{thJA}	≤ 50	
Thermal resistance, junction - ambient	R_{thJA}	≤ 100	
IEC climatic category, DIN IEC 68-1		55 / 150 / 56	

** when mounted on 1 " square PCB (FR4);for recommended footprint

Electrical Characteristics, at T_j = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain- source breakdown voltage V_{GS} = 0 V, I_D = 0.25 mA, T_j = 25 °C	$V_{(BR)DSS}$	100	-	-	V
Gate threshold voltage V_{GS}=$V_{DS,}$ I_D = 1 mA	$V_{GS(th)}$	2.1	3	4	
Zero gate voltage drain current V_{DS} = 100 V, V_{GS} = 0 V, T_j = 25 °C V_{DS} = 100 V, V_{GS} = 0 V, T_j = 125 °C	I_{DSS}	- -	0.1 10	1 100	µA
Gate-source leakage current V_{GS} = 20 V, V_{DS} = 0 V	I_{GSS}	-	10	100	nA
Drain-Source on-resistance V_{GS} = 10 V, I_D = 8.4 A	$R_{DS(on)}$	-	0.25	0.3	Ω

Electrical Characteristics, at T_j = 25°C, unless otherwise specified

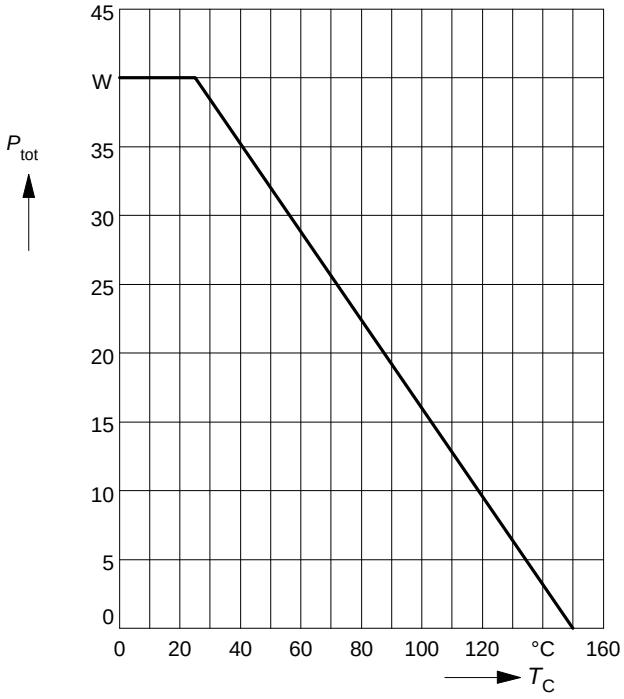
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Transconductance $V_{DS} \geq 2 * I_D * R_{DS(on)max}$, I_D = 8.4 A	g_{fs}	2	4.5	-	S
Input capacitance V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	C_{iss}	-	340	425	pF
Output capacitance V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	C_{oss}	-	80	100	
Reverse transfer capacitance V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	C_{rss}	-	30	40	
Turn-on delay time V_{DD} = 30 V, V_{GS} = 10 V, I_D = 3 A R_G = 50 Ω	$t_{d(on)}$	-	13	20	ns
Rise time V_{DD} = 30 V, V_{GS} = 10 V, I_D = 3 A R_G = 50 Ω	t_r	-	40	60	
Turn-off delay time V_{DD} = 30 V, V_{GS} = 10 V, I_D = 3 A R_G = 50 Ω	$t_{d(off)}$	-	50	75	
Fall time V_{DD} = 30 V, V_{GS} = 10 V, I_D = 3 A R_G = 50 Ω	t_f	-	35	55	

Electrical Characteristics, at T_j = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Reverse Diode					
Inverse diode continuous forward current T_C = 25 °C	I_S	-	-	8.4	A
Inverse diode direct current,pulsed T_C = 25 °C	I_{SM}	-	-	33.6	
Inverse diode forward voltage V_{GS} = 0 V, I_F = 16.8 A	V_{SD}	-	1.2	1.6	V
Reverse recovery time V_R = 30 V, I_F=I_S, di_F/dt = 100 A/µs	t_{rr}	-	90	135	ns
Reverse recovery charge V_R = 30 V, I_F=I_S, di_F/dt = 100 A/µs	Q_{rr}	-	0.35	0.55	µC

Power dissipation

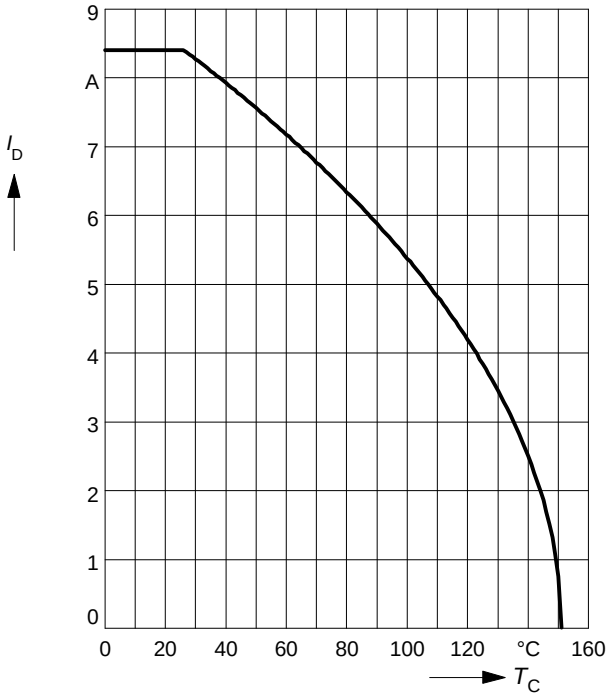
$P_{tot} = f(T_C)$



Drain current

$I_D = f(T_C)$

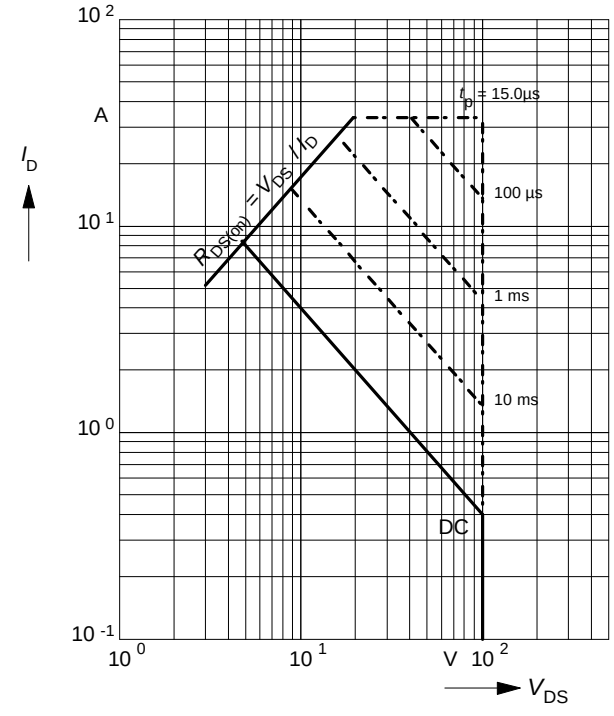
parameter: $V_{GS} \geq 10$ V



Safe operating area

$I_D = f(V_{DS})$

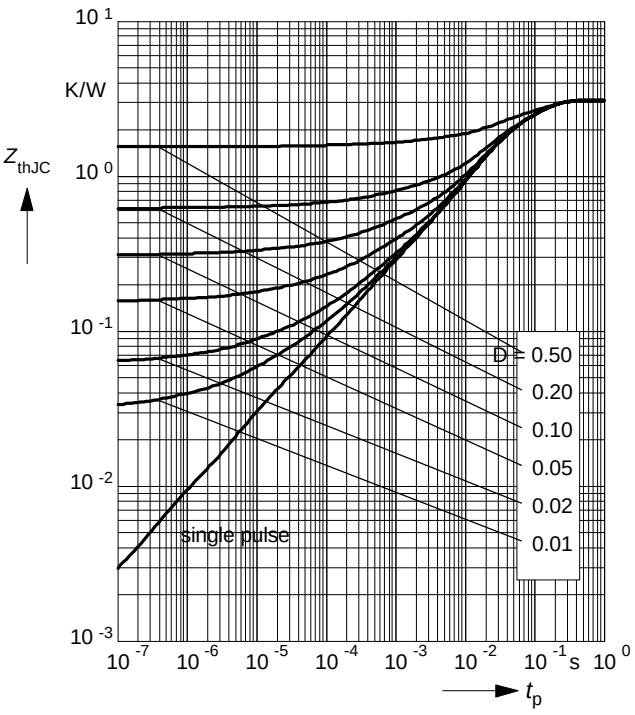
parameter: $D = 0.01$, $T_C = 25$°C



Transient thermal impedance

$Z_{th\,JC} = f(t_p)$

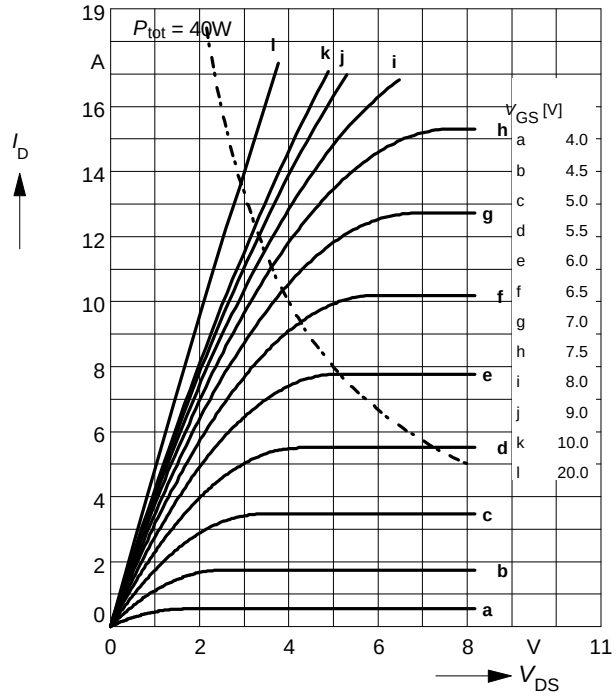
parameter: $D = t_p / T$



Typ. output characteristics

$I_D = f(V_{DS})$

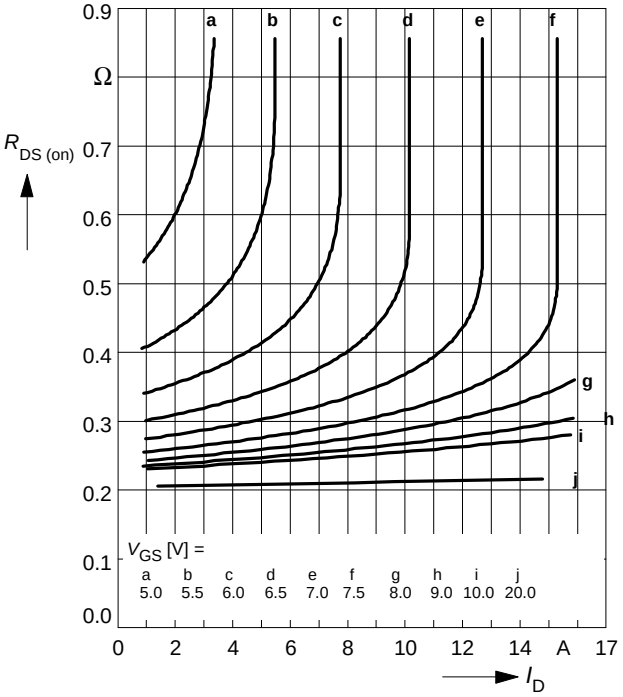
parameter: t_p = 80 µs



Typ. drain-source on-resistance

$R_{DS\,(on)} = f(I_D)$

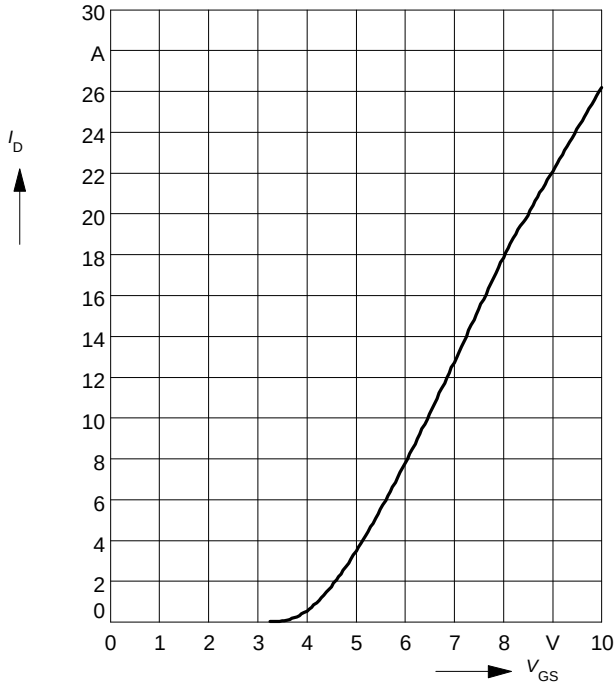
parameter: t_p = 80 µs, T_j = 25 °C



Typ. transfer characteristics $I_D = f(V_{GS})$

parameter: t_p = 80 µs

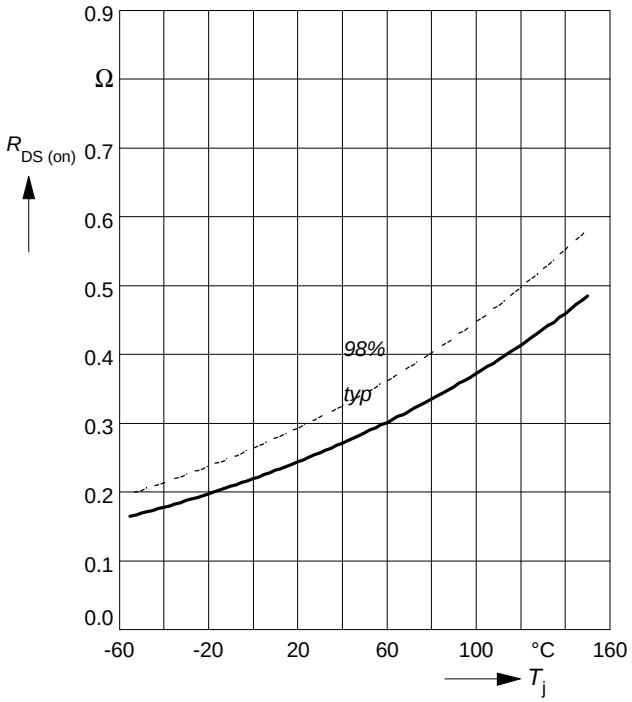
$V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$



Drain-source on-resistance

$R_{DS\ (on)} = f(T_j)$

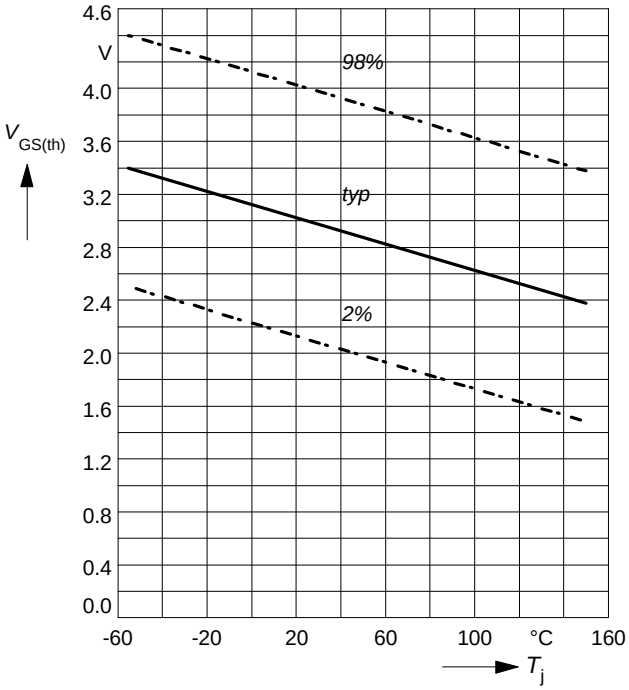
parameter: I_D = 8.4 A, V_{GS} = 10 V



Gate threshold voltage

$V_{GS\ (th)} = f(T_j)$

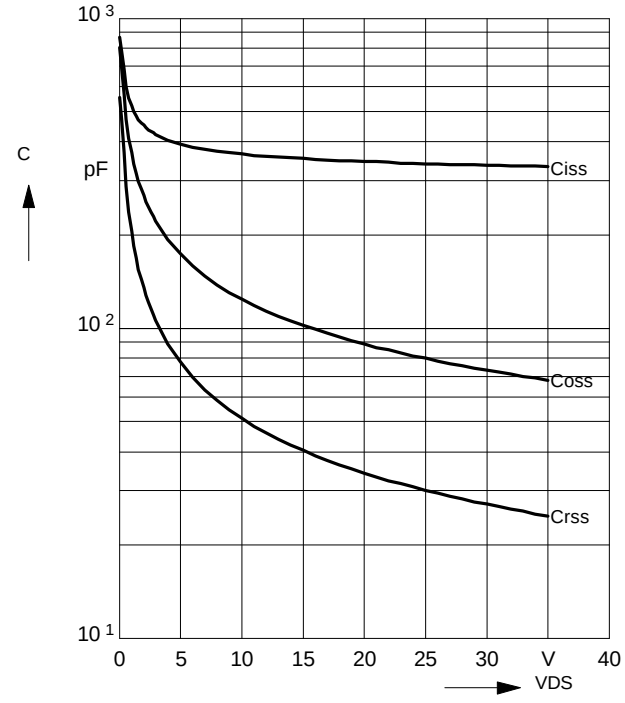
parameter: $V_{GS} = V_{DS}$, I_D = 1 mA



Typ. capacitances

$C = f(V_{DS})$

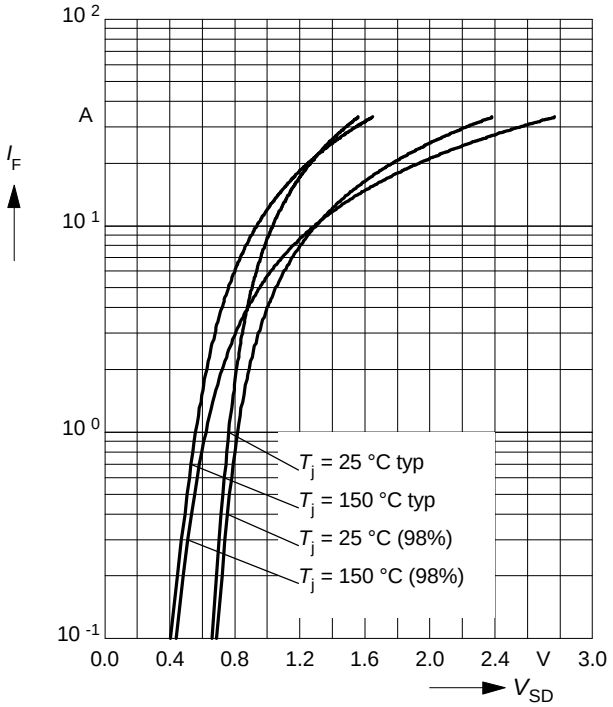
parameter: V_{GS} = 0V, f = 1MHz



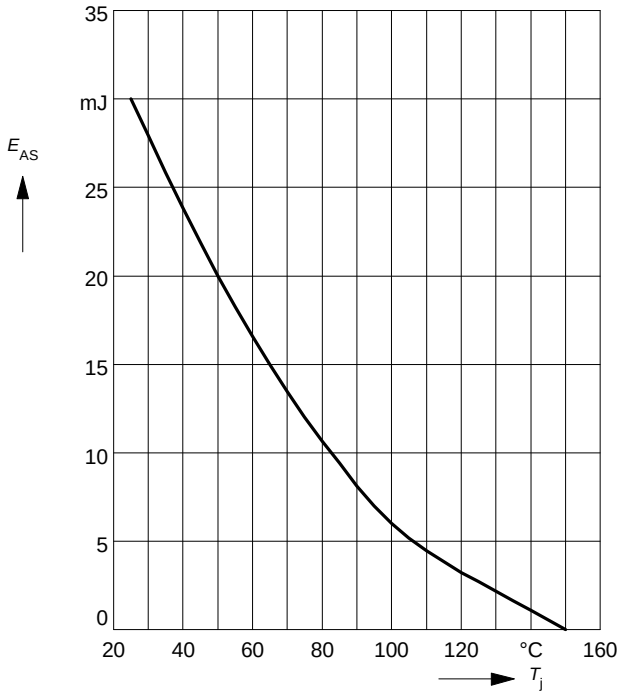
Forward characteristics of reverse diode

$I_F = f(V_{SD})$

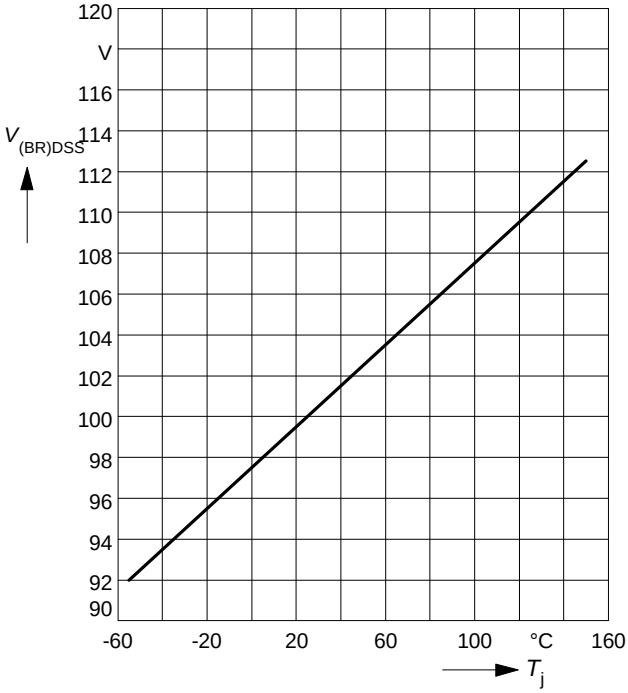
parameter: T_j, t_p = 80 µs



Avalanche energy $E_{AS} = f(T_j)$
parameter: I_D=8.4A, V_{DD} =25 V
R_{GS} =25 Ω , L = 850µH



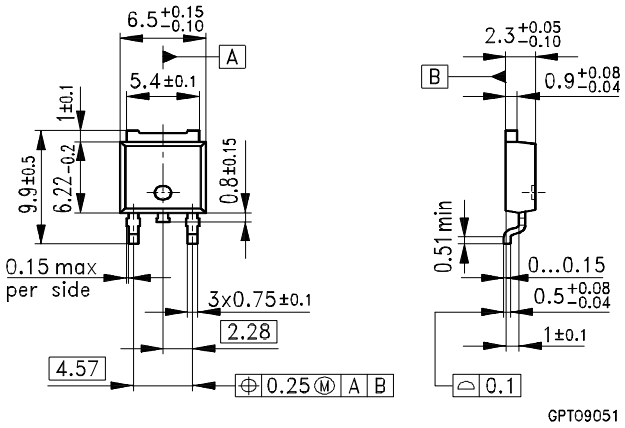
Drain-source breakdown voltage
$V_{(BR)DSS} = f(T_j)$



Package Outlines

P-TO252

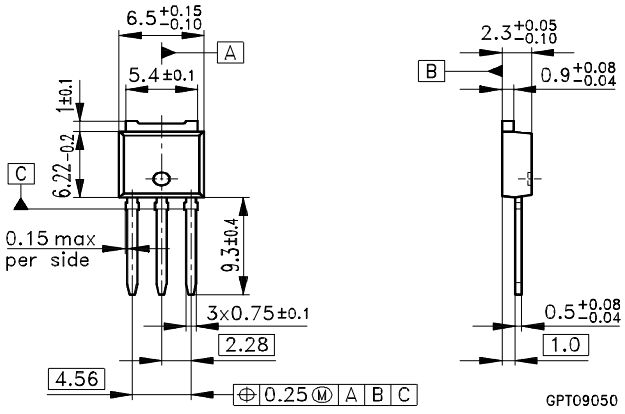
Dimension in mm



All metal surfaces tin plated, except area of cut.

P-TO251

Dimension in mm



All metal surfaces tin plated, except area of cut.